molex
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Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name	Molex Product Compliance	**E-Mail**	Product.Compliance@molex.com

Part Information

Part Number	0015246183	**Part Weight**	7.015283G
Part Name	MF Jr BMI RtAn Hdr Assy V0 SelGold 18Ckt		

Product Composition

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
MF Jr BMI RtAn Hdr Assy V0 SelGold 18Ckt	Assembly		100	7.015283
18CKT BLIND MATE HOUSING 4240418B1	Component		41.3668	2.902
PA66 NATURAL	Material		41.3668	2.902
PA66	Substance		35.5755	2.49572
Flame Retardant, ISO 1043-4 FR(30)	Substance		4.964	0.34824
Pentaerythritol tetrakis(3-(3,5-di-tert-butyl-4-hydroxyphenyl)propionate)	Substance	6683-19-8	0.4137	0.02902
Calcium distearate	Substance	1592-23-0	0.4137	0.02902
".720 X .042 SQ BANDO 228 Plt 30""SAu"	Assembly		23.4773	1.647
0.720 X .042 Sq Bando Pin 999	Component		22.7076	1.593
Cartridge Brass 70% Unplated	Material		22.7076	1.593
Copper	Substance	7440-50-8	15.8953	1.1151
Zinc (metal)	Substance	7440-66-6	6.8123	0.4779
Gold Plating	Material		0.1539	0.0108

Name	Type	CAS Number	Proportion (% Total)	Mass (Grams)
Cobalt	Substance	7440-48-4	0.0004	0.000027
Nickel	Substance	7440-02-0	0.0004	0.000027
Gold	Substance	7440-57-5	0.1532	0.010746
Tin Plating	Material		0.1539	0.0108
Tin	Substance	7440-31-5	0.1539	0.0108
Nickel Plating	Material		0.4618	0.0324
Nickel	Substance	7440-02-0	0.4618	0.032397
Further Additives	Substance	system	5E-05	0.000003
1.106 X .042 Sq Bando Pin 228 Plt	Assembly		35.1559	2.466283
1.106 X .042 Sq Bando Pin 999	Component		34.767	2.439
Cartridge Brass 70% Unplated	Material		34.767	2.439
Copper	Substance	7440-50-8	24.3369	1.7073
Zinc (metal)	Substance	7440-66-6	10.4301	0.7317
Gold Plating	Material		0.0479	0.003357
Cobalt	Substance	7440-48-4	0.0001	0.000008
Nickel	Substance	7440-02-0	0.0001	0.000008
Gold	Substance	7440-57-5	0.0476	0.00334
Tin Plating	Material		0.0588	0.004126
Tin	Substance	7440-31-5	0.0588	0.004126
Nickel Plating	Material		0.2822	0.0198
Nickel	Substance	7440-02-0	0.2822	0.019798
Further Additives	Substance	system	3E-05	0.000002

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)4578-DC (25 June 2020)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	150	Yes
Nickel	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
Nickel	Ep-Ni	*Note	997,500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
Copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes

***Note:** For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Part Name	Exemption

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH   Declaration Information

Regulatory Revision   IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	0015246183
Part Name	MF Jr BMI RtAn Hdr Assy V0 SelGold 18Ckt
Part Information	

	Hazardous Substances					
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MF Jr BMI RtAn Hdr Assy V0 SelGold 18Ckt	O	O	O	O	O	O
18CKT BLIND MATE HOUSING 4240418B1	O	O	O	O	O	O
".720 X .042 SQ BANDO 228 Plt 30""SAu"	O	O	O	O	O	O
0.720 X .042 Sq Bando Pin 999	O	O	O	O	O	O
1.106 X .042 Sq Bando Pin 228 Plt	O	O	O	O	O	O
1.106 X .042 Sq Bando Pin 999	O	O	O	O	O	O

Process Information

Component Plating / Surface Finish	MSn-Ni
Termination Base Alloy	Brass

Solder Alloy	N/A
Process Capability	WAVE
Maximum Exposure Time (seconds)	005
Maximum Process Temperature (C)	240
Maximum Cycles at Reflow Temperature	001
J-STD-020 Moisture Sensitivity Level	N/A

Aug 5, 2020